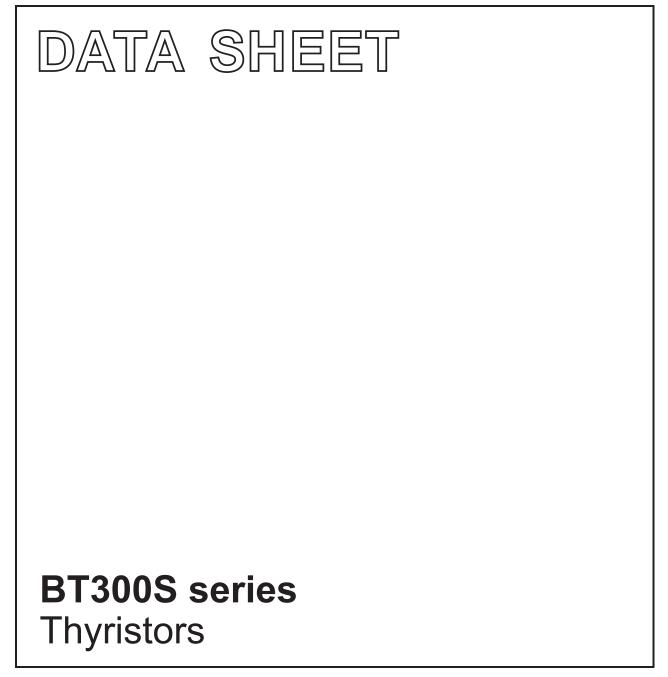
DISCRETE SEMICONDUCTORS



Product specification

September 1997



Thyristors

Product specification

BT300S series BT300M series

GENERAL DESCRIPTION

Glass passivated thyristors in a plastic envelope, suitable for surface mounting, intended for use in applications high requiring bidirectional blocking voltage capability and high thermal cycling performance. Typical applications include motor control, industrial and domestic lighting, heating and static switching.

PINNING - SOT428

PIN NUMBER	Standard S	Alternative M
1	cathode	gate
2	anode	anode
3	gate	cathode
tab	anode	anode

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	MAX.	UNIT
V _{DRM} , V _{RRM} I _{T(AV)} I _{T(RMS)} I _{TSM}	BT300S (or BT300M)- Repetitive peak off-state voltages Average on-state current RMS on-state current Non-repetitive peak on-state current	500R 500 5 8 65	600R 600 5 8 65	800R 800 5 8 65	V A A A

PIN CONFIGURATION

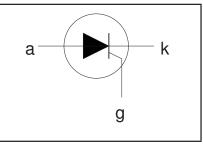
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____2

1

3

SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.		MAX.		UNIT
$V_{\text{drm}}, V_{\text{rrm}}$	Repetitive peak off-state voltages		-	-500R 500 ¹	-600R 600 ¹	-800R 800	V
I _{T(AV)} I _{T(RMS)} I _{TSM}	Average on-state current RMS on-state current Non-repetitive peak on-state current	half sine wave; $T_{mb} \le 107$ °C all conduction angles half sine wave; $T_j = 25$ °C prior to surge	-		5 8		A A
		t = 10 ms t = 8.3 ms	-		65 71		A A
l ² t dI _T /dt	I ² t for fusing Repetitive rate of rise of on-state current after		-		21 50		A²s A/μs
$\begin{matrix} I_{GM} \\ V_{GM} \\ P_{GM} \\ P_{GM} \\ P_{G(AV)} \\ T_{stg} \\ T_{j} \end{matrix}$	triggering Peak gate current Peak gate voltage Peak reverse gate voltage Peak gate power Average gate power Storage temperature Operating junction temperature	over any 20 ms period	- - - -40 -		2 5 5 0.5 150 125		ంఄన≦<<⋗

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15 A/ μ s.

NXP Semiconductors

Thyristors

Product specification

BT300S series BT300M series

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-mb}	Thermal resistance		-	-	2.2	K/W
R _{th j-a}	junction to mounting base Thermal resistance junction to ambient	pcb (FR4) mounted; footprint as in Fig.14	-	75	-	K/W

STATIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{GT}	Gate trigger current	$V_{\rm D} = 12 \text{ V}; \text{ I}_{\rm T} = 0.1 \text{ A}$	-	2	15	mA
	Latching current	$V_{\rm D} = 12 \text{ V}; \text{ I}_{\rm GT} = 0.1 \text{ A}$	-	10	40	mA
I _H	Holding current	$V_{\rm D} = 12 \text{ V}; I_{\rm GT} = 0.1 \text{ A}$	-	10	20	mA
İΫ _τ	On-state voltage	$I_{T} = 12 \text{ A}$	-	1.35	1.6	V
V _{GT}	Gate trigger voltage	$\dot{V}_{\rm D} = 12 \text{ V}; \text{ I}_{\rm T} = 0.1 \text{ A}$	-	0.6	1.5	V
<u> </u>		$V_{\rm D} = V_{\rm DBM(max)}; I_{\rm T} = 0.1 \text{ A}; T_{\rm i} = 125 \text{ °C}$	0.25	0.4	-	V
I _D , I _R	Off-state leakage current	$V_D = V_{DRM(max)}^{Orthm(max)}; V_R = V_{RRM(max)}; T_j = 125 \text{°C}$	-	0.1	0.5	mA

DYNAMIC CHARACTERISTICS

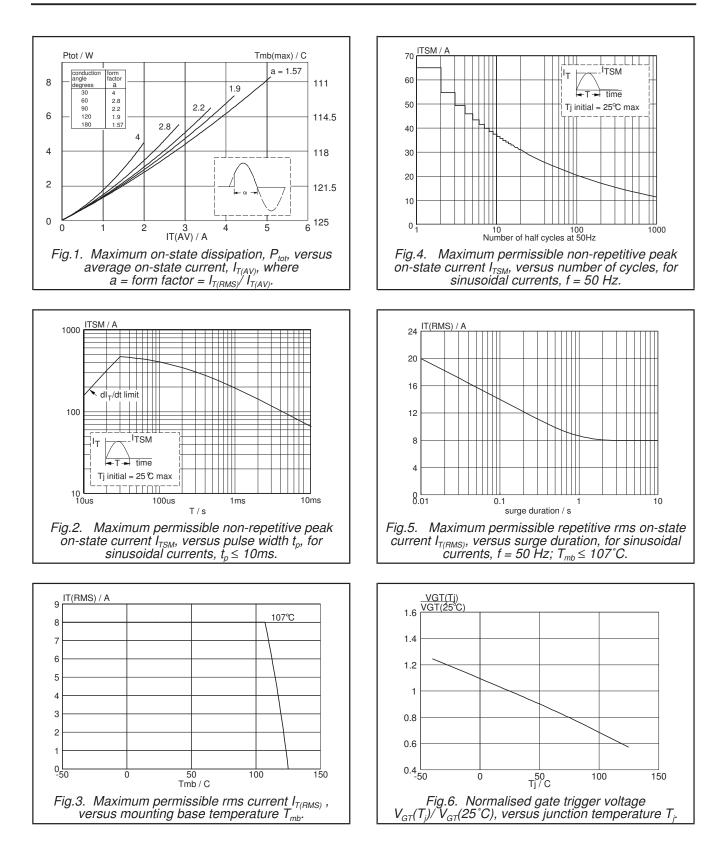
$T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV _D /dt	Critical rate of rise of off-state voltage	$V_{DM} = 67\% V_{DRM(max)}; T_j = 125 °C;$ exponential waveform.	50	100		Mue
		Gate open circuit $R_{GK} = 100 \Omega$	50 200	100	-	V/μs V/μs
t _{gt}	Gate controlled turn-on time	$I_{TM} = 10 \text{ A}; V_D = V_{DRM(max)}; I_G = 0.1 \text{ A};$ $dI_G/dt = 5 \text{ A}/\mu \text{s}$	-	2	-	μs
t _q	Circuit commutated turn-off time		-	70	-	μs

Product specification

Thyristors

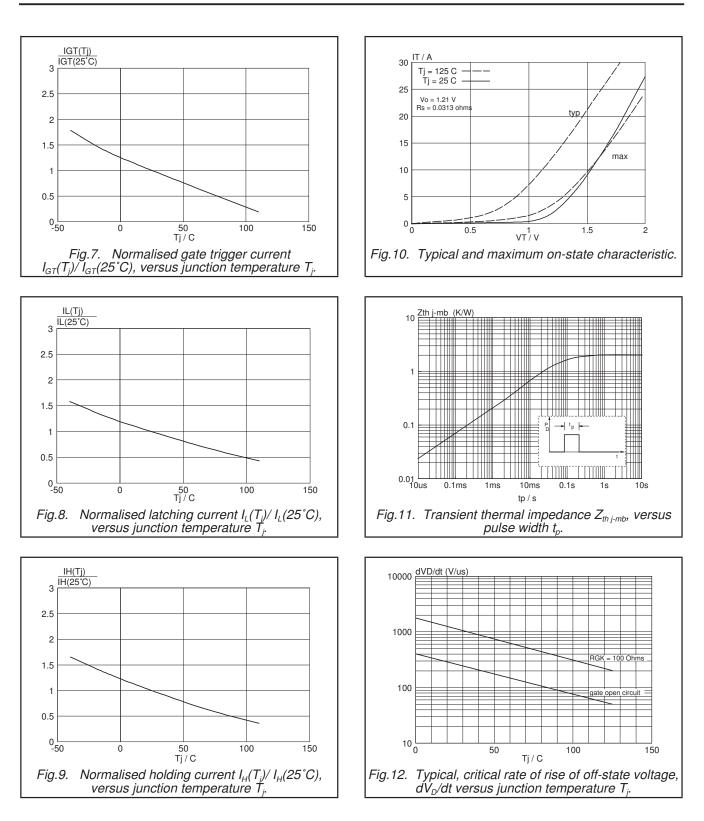
BT300S series BT300M series



Product specification

Thyristors

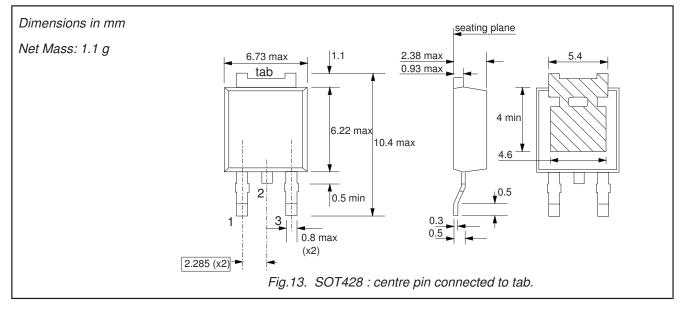
BT300S series BT300M series



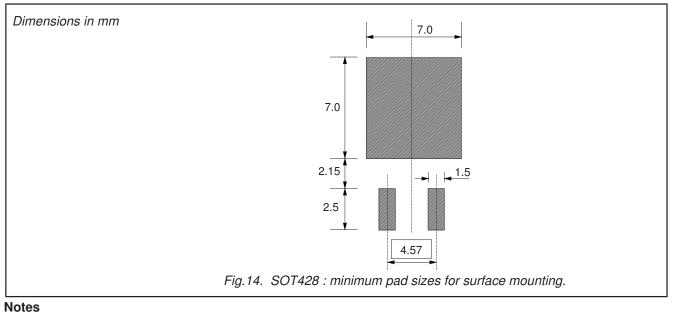
Thyristors

BT300S series BT300M series

MECHANICAL DATA



MOUNTING INSTRUCTIONS



1. Plastic meets UL94 V0 at 1/8".

Legal information

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Contact information

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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